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1753

Docket No.: 50352-020

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of	:	Customer Number: 20277
Shiroshi MATSUKI, et al.	:	Confirmation Number: 9915
Application No.: 09/944,344	:	Group Art Unit: 1753
Filed: September 04, 2001	:	Examiner: Edna Wong
For: MATERIAL FOR COPPER ELECTROPLATING, METHOD FOR MANUFACTURING SAME AND COPPER ELECTROPLATING METHOD		

**AMENDMENT and REQUEST FOR RECONSIDERATION**  
**UNDER 37 CFR § 1.111**

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This is a response to the non-final Office Action dated September 16, 2004. The above-referenced patent application has been amended as set forth below.

Please amend claims 1 and 2 as set forth in the "Amendments to the Claims" on pages 2 to 7 of this response.